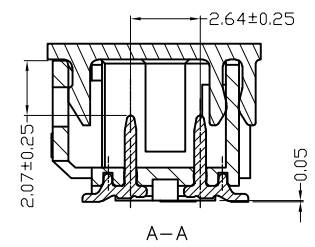
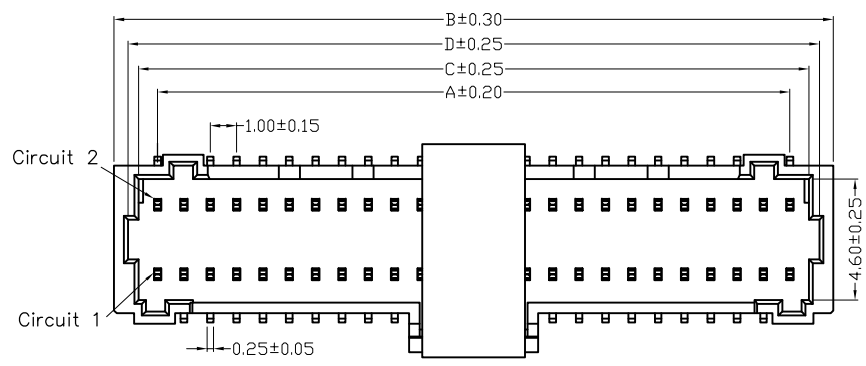
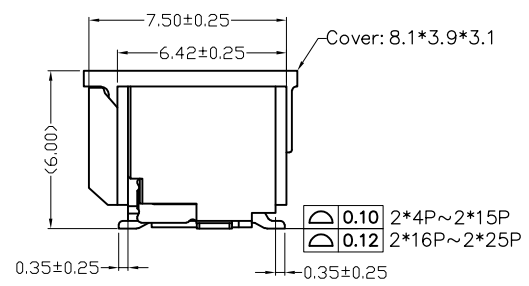
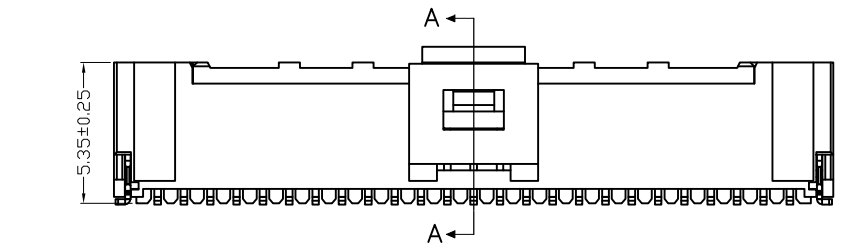


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



SPECIFICATIONS
Electrical
 Current Rating: 1.0A AC(rms)/DC
 Voltage Rating: 50V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 100 MΩ MIN
 Withstanding Voltage: 500V AC r.m.s
 Temperature Range—Operating: -25°C~+85°C
Material and Plating
 Housing: LCP (UL 94V-0)
 Pin: Phosphor bronze / Tin Plated
 Solder Tab: Brass / Tin Plated
 Mates With: FHG10007 Series

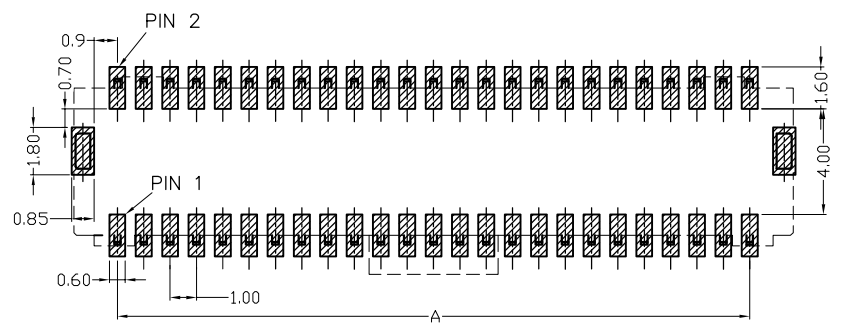


Circuits (n)	Part No.	Dimensions(mm)			
		A	B	C	D
20	FWF10012-D20S23NAM	9.00	12.30	10.45	11.25
24	FWF10012-D24S23NAM	11.00	14.30	12.45	13.25
30	FWF10012-D30S23NAM	14.00	17.30	15.45	16.25
36	FWF10012-D36S23NAM	17.00	20.30	18.45	19.25
40	FWF10012-D40S23NAM	19.00	22.30	20.45	21.25
50	FWF10012-D50S23NAM	24.00	27.30	25.45	26.25

Ordering Information

FWF 100 12 — D XX S 2 3 NA M
 1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 100—Pitch 1.00mm	3 Distinction No. 12	4 Row Option D—Double row	5 Circuits XX
6 Entry Angle S—180° Vertical	7 Plating 2—Tin Plated	8 Material—Resin 3—LCP	9 Color—Resin NA—Natural	10 Packaging M—Reel



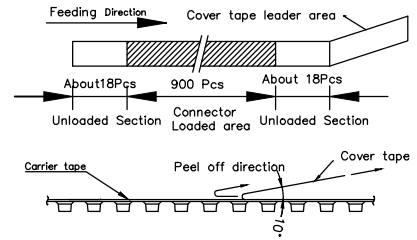
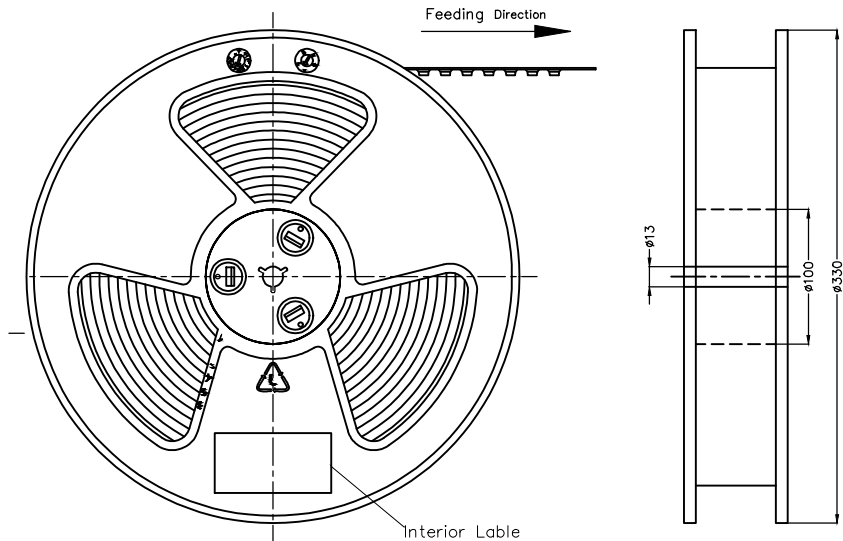
Recommended P.C.Board Layout
 General tolerances: ±.002(0.05)

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 02/AUG/23	PART NO. FWF10012-DXXS23NAM	ITEM NO. FWF10012	 Building Technology Cornerstone
	DESIGN UNITS METRIC	X. ±0.30	X.' ±5'	CHECKED BY GISELLE	DATE 02/AUG/23	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)	
SCALE 5:1	SIZE A4	X.XX ±0.15	X.XX' ±1'	DRAWN BY NICK	DATE 02/AUG/23	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

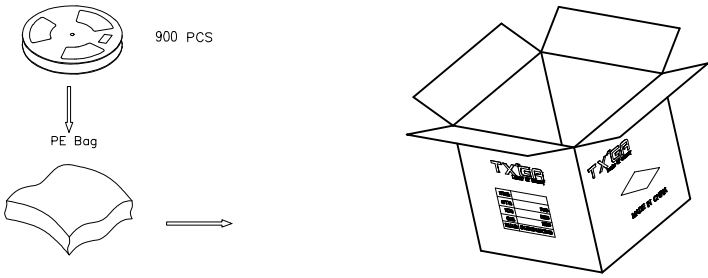
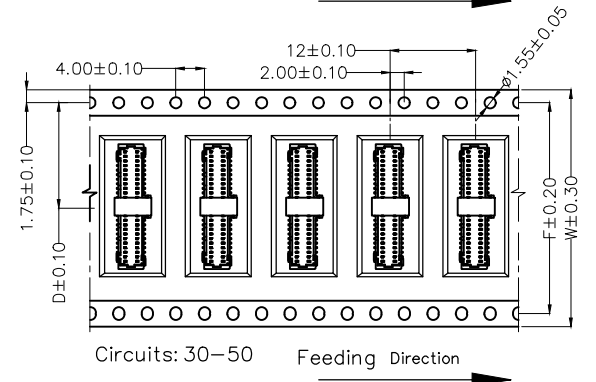
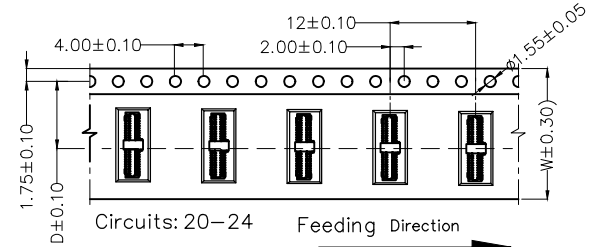
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

- 10 sprocket hole cumulative tolerance±0.2
- Carrier camber is within 1.0mm in 250mm
- Material: White Conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Peel off force of cover tape&carrier tape: 20g~130g(0.2N~1.3N)
- Component load per 13" reel: 900 pcs



Circuits (n)	Dimensions(mm)		
	D	W	F
20~24	11.50	24.00	-
30~36	14.20	32.00	28.40
40~50	20.20	44.00	40.40



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 02/AUG/23	PART NO. FWF10012-DXXS23NAM	ITEM NO. FWF10012	 Building Technology Cornerstone
	X. ±0.30	X.* ±5°	CHECKED BY GISELLE	DATE 02/AUG/23	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		
DESIGN UNITS METRIC	X.X ±0.20	X.X* ±2°	DRAWN BY NICK	DATE 02/AUG/23	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
SCALE 5:1	SIZE A4	X.XX ±0.15	X.XX* ±1°				
		X.XXX ±0.10	X.XXX* ±0.5°				